ZRC (S-PBGA-N98)  PLASTIC BALL GRID ARRAY

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar Junior™ BGA configuration
D. Falls within JEDEC M0-225
E. This package is lead-free.

MicroStar Junior BGA is a trademark of Texas Instruments.

4205321-3/A 07/03
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